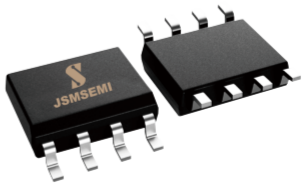
The JSM9435 uses advanced trench technology to provide excellent RDS(ON), shoot-through immunity, body diode characteristics and ultra-low gate resistance.

This device is ideally suited for use as a low side switch in Notebook CPU core power conversion.

JSM9435采用先进的沟道技术，提供出色的无线电数据系统（ON）、穿透抗扰性、体二极管特性和超低栅极电阻。该设备非常适合用作笔记本电脑CPU核心功率转换的低端开关。



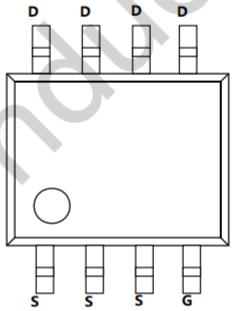
主要特性/Features

先进的沟槽工艺技术
Advanced trench process technology

高密度单元设计，超低导通电阻
High density cell design for ultra low on-resistance

高功率和电流处理能力
High power and current handing capability

引脚定义/pin definition



应用/Application

蓄电池开关 Battery Switch

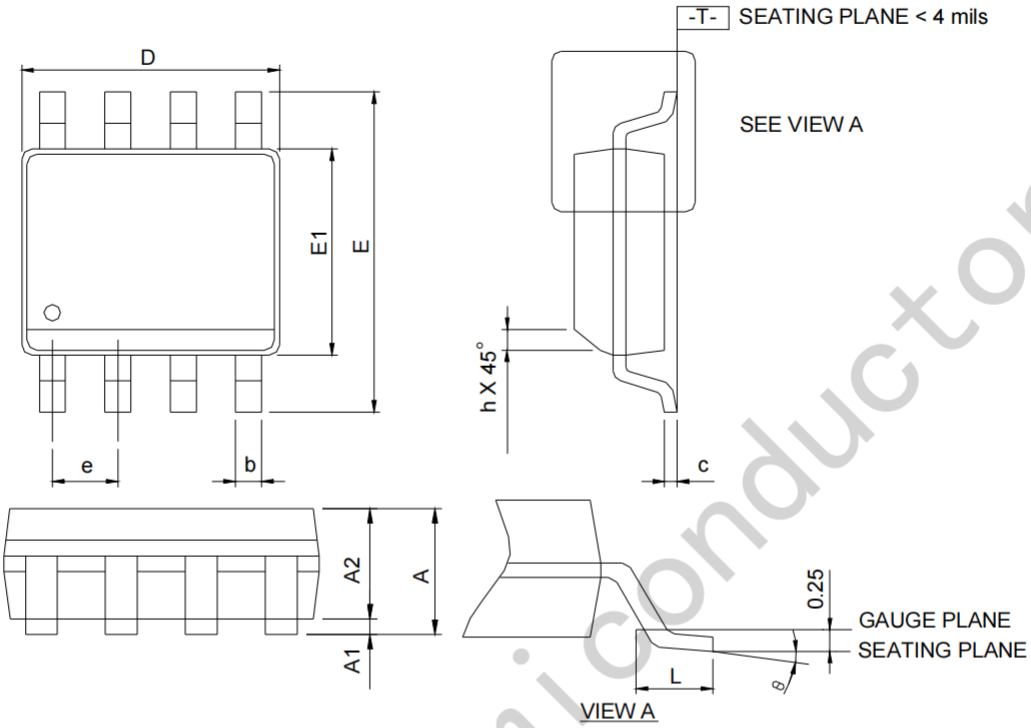
负荷开关 Load Switch

电性能参数/Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Description	Min.	Typ.	Max.	Test Conditions
V(BR)DSS	Drain-to-Source Breakdown Voltage	-30V			V_{GS} = 0V, I_D = -250μA
ID(Device Ref.)	Continuous Drain Current			-5.1A	T_J = 25°C
RDS(on)	Static Drain-to-Source On-Resistance		43mΩ	55mΩ	V_{GS} =-10V, I_D =-5.1A
RDS(on)	Static Drain-to-Source On-Resistance		62mΩ	90mΩ	V_{GS} =-4.5V, I_D =-4.2A
VGS(th)	Gate Threshold Voltage	-1.0V	-1.5V	-3.0V	V_{DS} = V_{GS}, I_D = -250μA
IDSS	Drain-to-Source Leakage Current			1μA	V_{DS} =-24V, V_{GS} = 0V, T_J = 25°C
IGSS	Gate-to-Source Leakage Current			±100nA	V_{GS} = ±20V
T_j	Operating Junction and Storage Temperature Range	-55°C to 150°C Max.			
TSTG					

Package Information

SOP-8



SYMBOL	SOP-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	1.75	-	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	-	0.049	-
b	0.31	0.51	0.012	0.020
c	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
h	0.25	0.50	0.010	0.020
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°

Note: 1. Follow JEDEC MS-012 AA.
2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "E" does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 10 mil per side.

RECOMMENDED LAND PATTERN